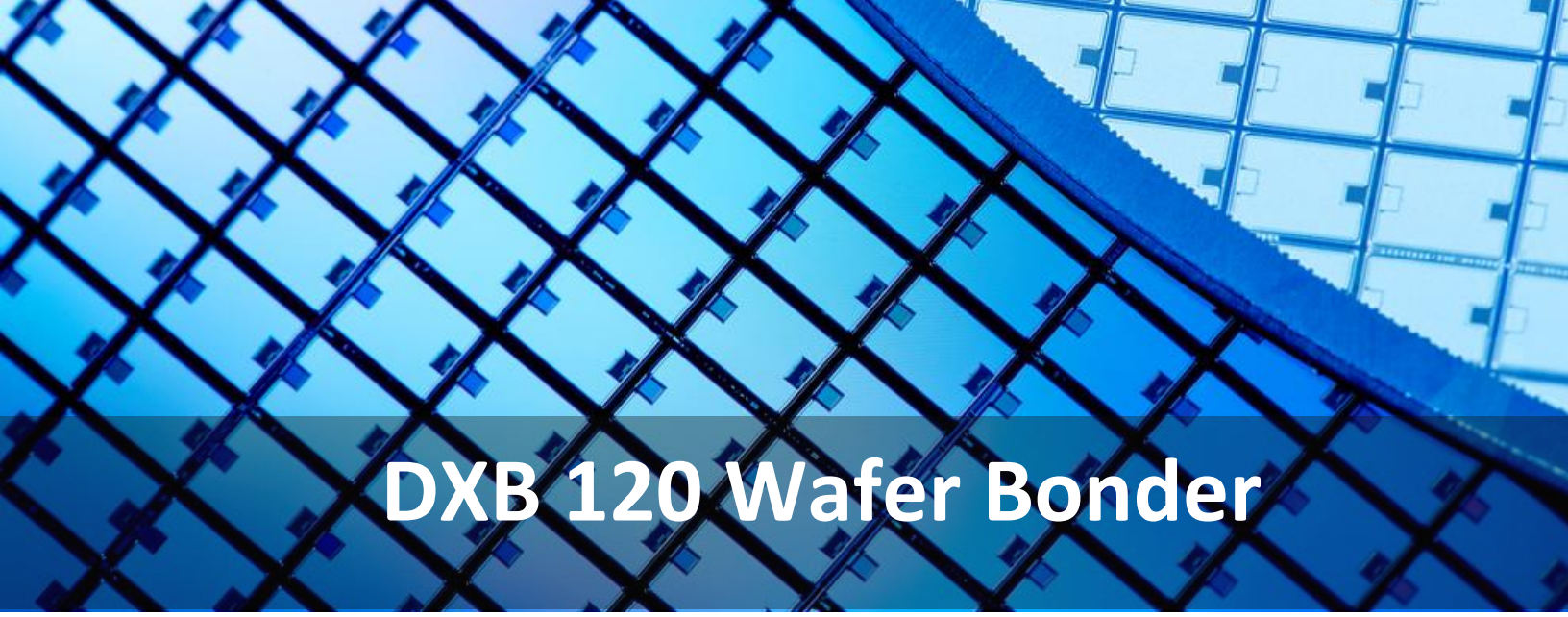


DXB 120 Wafer Bonder

DXB 120 Wafer Bonder

The DXB Wafer Bonder creates bonds for use when bonding wafers or glass to temporary substrates for subsequent wafer processing.

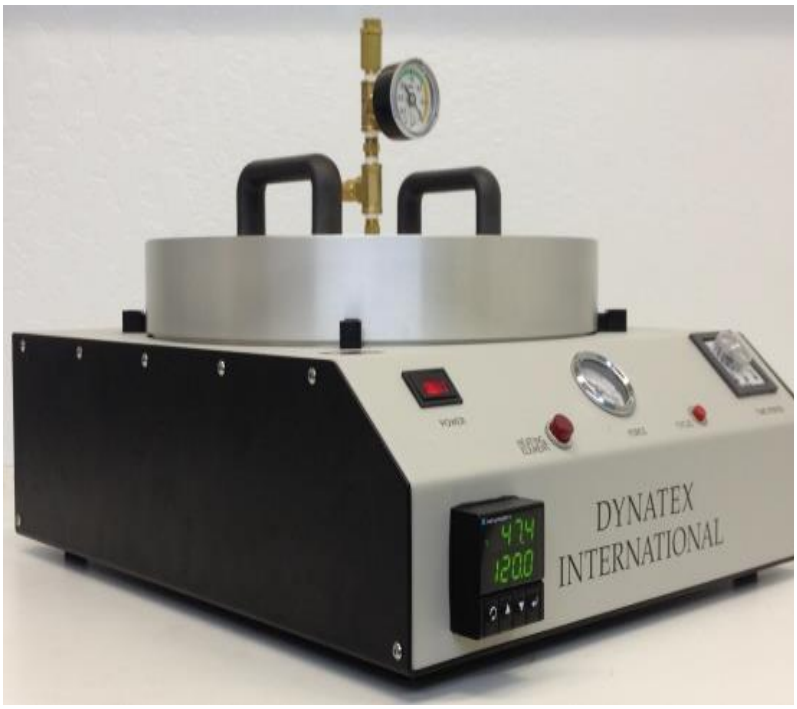
Applications

-Wafer Lapping

-Wafer Polishing

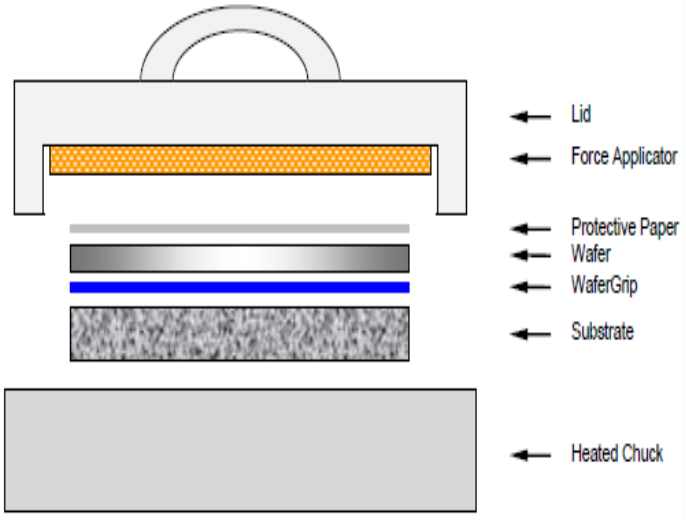
-Wafer Dicing

-Any other temporary wafer bonding process



Bonding a Wafer

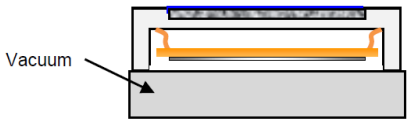
Once the bonder is at the desired temperature, the lid of the bonder is removed and the mounting substrate, adhesive, wafer and protective paper are set onto the heated chuck. The lid to the bonder is then placed back on and the cycle button is pressed. The bonder then evacuates the air from the chamber, applies the programmed amount of force for the programmed length of time, bonding the wafer to the substrate.



- Fast Efficient Bonding
- Controlled Bond Line
- No Messy Wax
- Operator Independent
- Simple Operation

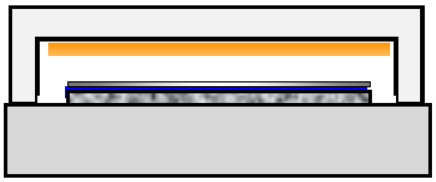
DXB Wafer Bonder

The diagram shows the wafer bonder chuck and lid, with the wafer, substrate and adhesive stack ready for bonding.



As vacuum develops in the bonding chamber, the force applicator is drawn down onto the bonding stack, thereby applying the bonding pressure.

Vacuum



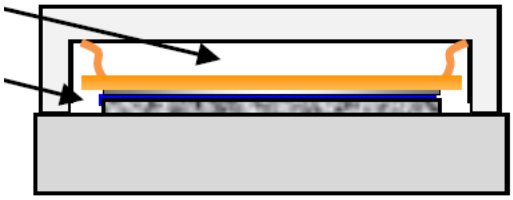
Controlling the Vacuum

By applying vacuum to the DXB Bonder lid, the force applicator can be held in the up position for zero force bonding

By applying partial vacuum to the DXB Bonder lid, the pressure applied by the force applicator can be controlled.

Partial Vacuum

Vacuum



DXB 120 Wafer Bonder Specifications

Bonding Chamber Size:	**11 inches (279 mm)**
Temperature Range :	**100-320° F**
Cycle Time Range:	**1 sec – 10 min**
Power Required:	**220/240 VAC 5 amp, 50/60Hz** **100/120 VAC 10 amp, 50/60Hz**
Vacuum Required:	**18-25 in Hg**
Environmental:	**60-80° F(15-27° C), 0-95 % Humidity (non-condensing)**
Dimensions:	

Height	**8 in (200 mm)**
Width	**15 in (375 mm)**
Depth	**17.5 in (440 mm)**
Chuck	**11.25 in (285 mm)**